	Type	L #	Hits	S arch T xt	DBs	Tim Stamp
1	IS&R	L1	2	("6614123").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/10 20:32
2	BRS	L2	14	("5365107" | "5397921" | "5409865" | "5851337" | "5877552" | "5905634" | "5933324" | "5977626" | "6020637" | "6146921" | "6201302" | "6246115" | "6323065" | "6400014").PN.	USPAT	2004/06/10 20:30
3	BRS	L3	71725	"head spreader" or "heat sink"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/10 20:32
4	BRS	L4	1320180	mold or molding or encapsulat$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/10 20:32
5	BRS	L5	1047476	chip or dice or die	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/10 20:33

	Type	L #	Hits	S arch Text	DBs	Time Stamp
6	BRS	L7	19296	"ball grid array" or BGA	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/10 20:34
7	BRS	L8	1046	3 and 4 and 5 and 7	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/10 20:34
8	BRS	L9	654	8 and (@ad<20010731)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/10 20:35

	Typ	L #	Hits	S arch Text	DBs	Tim Stamp
1	BRS	L5	71725	"head spreader" or "heat sink"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 10:54
2	BRS	L6	1320180	mold or molding or encapsulat$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 10:54
3	BRS	L7	1047476	chip or dice or die	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 10:54
4	BRS	L8	19296	"ball grid array" or BGA	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 10:54
5	BRS	L9	1046	("head spreader" or "heat sink") and (mold or molding or encapsulat$6) and (chip or dice or die) and ("ball grid array" or BGA)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 10:54

	Typ	L #	Hits	S arch Text	DBs	Time Stamp
6	IS&R	L3	2	("6614123").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 10:54
7	BRS	L4	14	("5365107" | "5397921" | "5409865" | "5851337" | "5877552" | "5905634" | "5933324" | "5977626" | "6020637" | "6146921" | "6201302" | "6246115" | "6323065" | "6400014").PN.	USPAT	2004/06/11 10:54
8	BRS	L10	654	(("head spreader" or "heat sink") and (mold or molding or encapsulat$6) and (chip or dice or die) and ("ball grid array" or BGA)) and (@ad<20010731)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 11:05
9	BRS	L12	283	"black copper oxide"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 11:06
10	BRS	L13	676	"NaClO.sub.2"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 11:07

	Typ	L #	Hits	S arch Text	DBs	Tim Stamp
11	BRS	L15	1017	micro-etch$6 or microetch$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 11:07
12	BRS	L16	7892869	treat$6 or heat$6 or thermally$6 or cur$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 11:08
13	BRS	L17	7955510	undersurface or bottom or underneath or below or lower or base	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 11:09
14	BRS	L18	8851	17 near4 5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 11:10
15	BRS	L19	8848	16 same 18	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 11:11

	Typ	L #	Hits	S arch T xt	DBs	Tim Stamp
16	BRS	L20	878	19 same copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 11:12
17	BRS	L23	878	20 same 16	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 11:12
18	BRS	L24	62	23 and 8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 11:19
19	BRS	L25	8	(cu or copper) near8 13	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 11:24
20	IS&R	L41	582	(438/122).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 11:24

	Typ	L #	Hits	S arch Text	DBs	Time Stamp
21	IS&R	L43	725	(438/126).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/11 11:33

	Typ	L #	Hits	Search T xt	DBs	Time Stamp
1	BRS	L1	71725	"head spreader" or "heat sink"	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/06/12 15:49
2	BRS	L2	132018 0	mold or molding or encapsulat$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/06/12 15:49
3	BRS	L3	104747 6	chip or dice or die	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/06/12 15:49
4	BRS	L4	19296	"ball grid array" or BGA	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/06/12 15:49
5	BRS	L5	1046	("head spreader" or "heat sink") and (mold or molding or encapsulat$6) and (chip or dice or die) and ("ball grid array" or BGA)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/06/12 15:49

	Type	L #	Hits	S arch Text	DBs	Tim Stamp
6	BRS	L9	283	"black copper oxide"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/12 15:49
7	BRS	L10	676	"NaClO.sub.2"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/12 15:49
8	BRS	L11	1017	micro-etch$6 or microetch$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/12 15:49
9	BRS	L12	7892869	treat$6 or heat$6 or thermally$6 or cur$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/12 15:50
10	BRS	L13	7955510	undersurface or bottom or underneath or below or lower or base	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/12 15:50

	Typ	L #	Hits	Search Text	DBs	Tim Stamp
11	BRS	L14	8851	(undersurface or bottom or underneath or below or lower or base) near4 ("head spreader" or "heat sink")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/12 15:50
12	BRS	L15	8848	(treat$6 or heat$6 or thermally$6 or cur$6) same ((undersurface or bottom or underneath or below or lower or base) near4 ("head spreader" or "heat sink"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/12 15:50
13	BRS	L16	878	((treat$6 or heat$6 or thermally$6 or cur$6) same ((undersurface or bottom or underneath or below or lower or base) near4 ("head spreader" or "heat sink"))) same copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/12 15:51
14	IS&R	L6	2	("6614123").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/12 15:51
15	BRS	L7	14	("5365107" "5397921" "5409865" "5851337" "5877552" "5905634" "5933324" "5977626" "6020637" "6146921" "6201302" "6246115" "6323065" "6400014").PN.	USPAT	2004/06/12 15:51

	Typ	L #	Hits	Search T xt	DBs	Tim Stamp
16	BRS	L8	654	(("head spreader" or "heat sink") and (mold or molding or encapsulat$6) and (chip or dice or die) and ("ball grid array" or BGA)) and (@ad<20010731)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/06/12 15:51
17	BRS	L17	878	((((treat$6 or heat$6 or thermally$6 or cur$6) same ((undersurface or bottom or underneath or below or lower or base) near4 ("head spreader" or "heat sink"))) same copper) same (treat$6 or heat$6 or thermally$6 or cur$6)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/06/12 15:52
18	BRS	L18	62	(((((treat$6 or heat$6 or thermally$6 or cur$6) same ((undersurface or bottom or underneath or below or lower or base) near4 ("head spreader" or "heat sink"))) same copper) same (treat$6 or heat$6 or thermally$6 or cur$6)) and ("ball grid array" or BGA)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/06/12 15:52
19	BRS	L19	8	(cu or copper) near8 "NaClO.sub.2"	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/06/12 15:52
20	IS&R	L20	582	(438/122).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/06/12 15:52

	Type	L #	Hits	S arch T xt	DBs	Tim Stamp
21	IS&R	L21	725	(438/126).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/06/12 15:52
22	BRS	L22	14	("5365107" "5397921" "5409865" "5851337" "5877552" "5905634" "5933324" "5977626" "6020637" "6146921" "6201302" "6246115" "6323065" "6400014").PN.	USPAT	2004/06/12 16:06
23	IS&R	L23	871	(257/783).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/06/12 16:06
24	IS&R	L27	2	("5328811").PN.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/06/12 16:15
25	IS&R	L28	2	("5977626").PN.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/06/12 16:15

	Typ	L #	Hits	Search Txt	DBs	Time Stamp
26	IS&R	L29	3273	(257/787).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/12 16:18
27	IS&R	L30	672	(257/796).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/12 17:14
28	IS&R	L31	326	(257/791).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/12 17:45